L Number	Hits	Search Text	DB	Time stamp
	338712	Cu or copper	USPAT;	2003/04/30
1			US-PGPUB	12:11
-	263262	barrier or SiN or "silicon nitride" or "copper diffusion	USPAT;	2003/04/30 ~
i		prevention" or "copper barrier"	US-PGPUB	12:11
-	457614	nitriding or nitrogen or ammonia	USPAT;	2003/04/30
1			US-PGPUB	12:11
-	20650	(Cu or copper) and (barrier or SiN or "silicon nitride" or	USPAT;	2003/04/30
		"copper diffusion prevention" or "copper barrier") and	US-PGPUB	11:51
1		(nitriding or nitrogen or ammonia)	**************************************	
-	342211	@ad>20010221 or @rlad>20010221	USPAT; US-PGPUB	2003/04/30
1		400) 10 in 000 half and 11 and	US-PGPUB USPAT;	11:51 2003/04/30
- 1	16434	((Cu or copper) and (barrier or SiN or "silicon nitride" or	US-PGPUB	11:52
i		"copper diffusion prevention" or "copper barrier") and	03-FGF 0B	11.52
- 1		(nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)		1
	566	(@Had>20010221) 438/627.ccls.	USPAT;	2003/04/30
-	200	430/02/.ccis.	US-PGPUB	11:52
1	161	(((Cu or copper) and (barrier or SiN or "silicon nitride" or	USPAT:	2003/04/30
-	101	"copper diffusion prevention" or "copper barrier") and	US-PGPUB	11:52
		(nitriding or nitrogen or ammonia)) not (@ad>20010221 or	55 1 GI 5B	1
3		(mittaing of introgen of annitonal) not (@ad>20010221 of @rlad>20010221) and 438/627.ccls.	1	1
- 1	224	removing with "copper oxide"	USPAT;	2003/04/30
	224	removing with copper oxide	US-PGPUB	12:15
_	6	((((Cu or copper) and (barrier or SiN or "silicon nitride" or	USPAT:	2003/04/30
	U	"copper diffusion prevention" or "copper barrier") and	US-PGPUB	12:01
		(nitriding or nitrogen or ammonia)) not (@ad>20010221 or	00 10100	1
1		@rlad>20010221)) and 438/627.ccls.) and (removing with	ł	
1		"copper oxide")		1
- 1	155	438/630.ccls.	USPAT;	2003/04/30
1	-55	100/00	US-PGPUB	12:01
-	24	(((Cu or copper) and (barrier or SiN or "silicon nitride" or	USPAT;	2003/04/30
- 1		"copper diffusion prevention" or "copper barrier") and	US-PGPUB	12:02
1		(nitriding or nitrogen or ammonia)) not (@ad>20010221 or		
- 1		@rlad>20010221)) and 438/630.ccls.		
- 1	2	(removing with "copper oxide") and ((((Cu or copper) and	USPAT;	2003/04/30
1		(barrier or SiN or "silicon nitride" or "copper diffusion	US-PGPUB	12:02
1		prevention" or "copper barrier") and (nitriding or nitrogen or	1	
1		ammonia)) not (@ad>20010221 or @rlad>20010221)) and	1	1
1		438/630.ccls.)	1	
- 1	532	438/631.ccls.	USPAT;	2003/04/30
			US-PGPUB	12:02
-	43	(((Cu or copper) and (barrier or SiN or "silicon nitride" or	USPAT;	2003/04/30
- 0		"copper diffusion prevention" or "copper barrier") and	US-PGPUB	12:02
- 1		(nitriding or nitrogen or ammonia)) not (@ad>20010221 or	1	
1)		@rlad>20010221)) and 438/631.ccls.	TIOD ATE	
- 11	1	(removing with "copper oxide") and ((((Cu or copper) and	USPAT;	2003/04/30
- 1		(barrier or SiN or "silicon nitride" or "copper diffusion	US-PGPUB	12:02
1		prevention" or "copper barrier") and (nitriding or nitrogen or	1	1
J		ammonia)) not (@ad>20010221 or @rlad>20010221)) and	1	
.		438/631.ccls.)	HODATA	0000/04/00
- 1	174	438/635.ccls.	USPAT;	2003/04/30
		(1/O O'N on "o'lloon - '' - "	US-PGPUB USPAT;	2003/04/30
- 17	20	(((Cu or copper) and (barrier or SiN or "silicon nitride" or	USPAT; US-PGPUB	12:02
		"copper diffusion prevention" or "copper barrier") and	US-FGFUB	12.02
1.0		(nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and 438/635.ccls.	1	
	_		USPAT;	2003/04/30
-	2	(removing with "copper oxide") and ((((Cu or copper) and	US-PGPUB	12:04
1		(barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or	CO-1 GI UB	12.04
1		ammonia)) not (@ad>20010221 or @rlad>20010221)) and	1	
1			1	
ì	6=0	438/635.ccls.) 438/643.ccls.	USPAT:	2003/04/30
- 1	670	430/043.043.	US-PGPUB	12:05

r=	182	(((Cu or copper) and (barrier or SiN or "silicon nitride" or	USPAT;	2003/04/30
-	102	"copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or	US-PGPUB	12:05
	1	@rlad>20010221)) and 438/643.ccls.	1	l
-	3	(removing with "copper oxide") and ((((Cu or copper) and	USPAT;	2003/04/30
1	1	(barrier or SiN or "silicon nitride" or "copper diffusion	US-PGPUB	12:05
1		prevention" or "copper barrier") and (nitriding or nitrogen or	1	
1	1	ammonia)) not (@ad>20010221 or @rlad>20010221)) and		
		438/643.ccls.) 438/645.ccls.	USPAT:	2003/04/30
1	171	430/045.008.	US-PGPUB	12:05
i _	19	(((Cu or copper) and (barrier or SiN or "silicon nitride" or	USPAT:	2003/04/30
	-	"copper diffusion prevention" or "copper barrier") and	US-PGPUB	12:05
		(nitriding or nitrogen or ammonia)) not (@ad>20010221 or		-
l		@rlad>20010221)) and 438/645.ccls.		
-	1	(removing with "copper oxide") and ((((Cu or copper) and	USPAT;	2003/04/30
	1	(barrier or SiN or "silicon nitride" or "copper diffusion	US-PGPUB	12:05
		prevention" or "copper barrier") and (nitriding or nitrogen or ammonia)) not (@ad>20010221 or @rlad>20010221)) and		
		438/645.ccls.)	1	1
l <u>.</u>	844	438/687.ccls.	USPAT:	2003/04/30
	344	10-//	US-PGPUB	12:05
-	201	(((Cu or copper) and (barrier or SiN or "silicon nitride" or	USPAT;	2003/04/30
		"copper diffusion prevention" or "copper barrier") and	US-PGPUB	12:06
Ì	1	(nitriding or nitrogen or ammonia)) not (@ad>20010221 or		Í
		@rlad>20010221)) and 438/687.ccls.	****	
-	11	(removing with "copper oxide") and ((((Cu or copper) and	USPAT;	2003/04/30
l		(barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper barrier") and (nitriding or nitrogen or	US-PGPUB	12:10
		ammonia)) not (@ad>20010221 or @rlad>20010221)) and	1	ł
!	1	438/687.ccls.)	l	1
-	366	438/906.ccls.	USPAT:	2003/04/30
ĺ	0	10-7,7	US-PGPUB	12:10
-	32	(((Cu or copper) and (barrier or SiN or "silicon nitride" or	USPAT;	2003/04/30
		"copper diffusion prevention" or "copper barrier") and	US-PGPUB	12:10
		(nitriding or nitrogen or ammonia)) not (@ad>20010221 or		
		@rlad>20010221)) and 438/906.ccls.	USPAT:	2003/04/30
-	1	(removing with "copper oxide") and (((Cu or copper) and (barrier or SiN or "silicon nitride" or "copper diffusion	US-PGPUB	12:10
		prevention" or "copper barrier") and (nitriding or nitrogen or	00 10102	12.110
		ammonia)) not (@ad>20010221 or @rlad>20010221)) and		
	1	438/906.ccls.)		
-	24	438/for.111.ccls.	EPO; JPO;	2003/04/30
		La company de la	DERWENT	12:10
-	237858	nitriding or nitrogen or ammonia	EPO; JPO; DERWENT	2003/04/30
	158050	barrier or SiN or "silicon nitride" or "copper diffusion	EPO; JPO;	12:11 2003/04/30
-	158052	prevention" or "copper barrier"	DERWENT	12:11
	592726	Cu or copper	EPO; JPO;	2003/04/30
	3,2,20		DERWENT	12:11
-	0	438/for.111.ccls. and ((nitriding or nitrogen or ammonia) and	EPO; JPO;	2003/04/30
		(barrier or SiN or "silicon nitride" or "copper diffusion	DERWENT	12:11
		prevention" or "copper barrier") and (Cu or copper))	nno me	
-	1201	438/for.355.ccls.	EPO; JPO;	2003/04/30
	1	((-it-iding on piters on on ammonia) and (homis CIN	DERWENT EPO: JPO:	12:11 2003/04/30
1-	0	((nitriding or nitrogen or ammonia) and (barrier or SiN or "silicon nitride" or "copper diffusion prevention" or "copper	DERWENT	12:12
	1	barrier") and (Cu or copper) and 438/for.355.ccls.	DEKTENI	*****
-	393	(nitriding or nitrogen or ammonia) and (barrier or SiN or	EPO; JPO;	2003/04/30
	373	"silicon nitride" or "copper diffusion prevention" or "copper	DERWENT	12:12
1		barrier") and (Cu or copper)		
-	165	removing with "copper oxide"	EPO; JPO;	2003/04/30
L	1		DERWENT	12:15

-	2 ((nitriding or nitrogen or ammonia) and (barrier or SiN or	EPO; JPO;	2003/04/30
}	"silicon nitride" or "copper diffusion prevention" or "copper	DERWENT	12:15
l	barrier") and (Cu or copper)) and (removing with "copper	1	
L	oxide")		